

This listing of claims will replace all prior versions and listings of claims in this application:

b.) Listing of Claims

1. (currently amended) An optical fiber array apparatus for providing optical connections to an integrated optics chip or optoelectronic optical device, comprising:
- a) a V-groove chip having a V-groove, a rear portion, a front portion, and a front face ~~opposite the rear portion~~, and
 - b) an optical fiber disposed in the V-groove, wherein:
 - 1) the optical fiber is bonded to the rear portion of the V-groove chip,
 - 2) the optical fiber is not bonded to the front portion of the V-groove chip, which is in proximity to the integrated optics chip or optoelectronic device, and
 - 3) wherein the optical fiber extends from the rear portion.
2. (original) The apparatus of claim 1 wherein the optical fiber has an endface located within 1 millimeter of the front face.
3. (original) The apparatus of claim 1 wherein the V-groove chip has a wick stop trench between the rear portion and the front portion.
4. (original) The apparatus of claim 1 further comprising a lid disposed on top of the optical fibers in the rear portion.
5. (original) The apparatus of claim 1 wherein the optical fiber has an endface that is flush with the front face.
6. (original) The apparatus of claim 1 wherein the front portion is 1-10 millimeters long.
7. (original) The apparatus of claim 1 wherein the rear portion is 0.2-5 millimeters long.

8. (original) The apparatus of claim 1 wherein the front portion has pits for receiving alignment spheres.
9. (original) The apparatus of claim 1 wherein the front face is angled nonperpendicularly with respect to the optical fiber.
10. (original) The apparatus of claim 9 wherein the front face is angled forward.
11. (currently amended) The apparatus of claim 1 wherein the V-grooves ~~are~~ is large in the front portion so that a location of an optical fiber is not fully determined by the V-groove in the front portion.
12. (original) The apparatus of claim 11 wherein the V-groove in the front portion has a flat bottom surface.

17. ~~13.~~ (currently amended) An optical fiber array apparatus for providing optical connections to an integrated optics chip or optoelectronic ~~optical~~ device, comprising:

- a) a V-groove chip having a V-groove, a rear portion, a middle portion, a bonded front portion, and a front face ~~opposite the rear portion~~, and
- b) an optical fiber disposed in the V-groove, wherein:
- 1) the optical fiber is bonded to the rear portion of the V-groove chip,
 - 2) the optical fiber is not bonded to the middle portion of the V-groove chip,
 - 3) the optical fiber is bonded to the bonded front portion of the V-groove chip, which is in proximity to the integrated optics chip or optoelectronic device, and
 - 4) wherein the optical fiber extends from the rear portion.

18. ~~14.~~ (original) The apparatus of claim ~~15~~ ¹⁷ wherein the optical fiber has an endface located within 1 millimeter of the front face.

19. ~~15.~~ (currently amended) The apparatus of claim ~~13~~ ¹⁷ wherein the V-groove chip has a wick stop trench between the rear portion and the bonded front portion.

16. (original) The apparatus of claim 15 wherein the V-groove chip has a wick stop trench between the middle portion and the bonded front portion.
17. (original) The apparatus of claim 15 further comprising a lid disposed on top of the optical fibers in the rear portion.
18. (original) The apparatus of claim 15 wherein the optical fiber has an endface that is flush with the front face.
19. (original) The apparatus of claim 15 wherein the bonded front portion is 0.2-2 millimeters long.
20. (original) The apparatus of claim 15 wherein the rear portion is 0.2-5 millimeters long.
21. (original) The apparatus of claim 15 wherein the front portion has pits for receiving alignment spheres.
22. (original) The apparatus of claim 15 wherein the front face is angled nonperpendicularly with respect to the optical fiber.
23. (currently amended) A method for coupling an optical fiber to an integrated optics chip or optoelectronic optical device disposed on a substrate, comprising the steps of:
- a) bonding the optical fiber to only a rear portion of a V-groove chip having a the rear portion and a front portion;
 - b) bonding the optical fiber and front portion of the V-groove chip to the substrate so that the optical fiber is aligned with the optical integrated optics chip or optoelectronic device.
24. (currently amended) The method of claim 23 further comprising the step of disposing the optical fiber in a V-groove in the substrate, wherein the substrate V-groove is aligned with the integrated optics chip or optoelectronic optical device.

13. ~~25~~. (new) The apparatus of claim 1 wherein the integrated optics chip or optoelectronic device is mounted on a substrate, which is a submount chip or substrate chip.

14. ~~26~~. (new) The apparatus of claim ¹³~~25~~ wherein the substrate cooperates with the front portion of the V-groove chip to hold the optical fiber.

15. ~~27~~. (new) The apparatus of claim ¹³~~25~~ wherein the substrate comprises a V-groove, the optical fiber being held between the V-groove of the V-groove chip and the V-groove of the substrate.

16. ~~28~~. (new) The apparatus of claim ¹³~~25~~ wherein the substrate comprises a V-groove, the optical fiber being held between the V-groove of the front portion of the V-groove chip and the substrate.

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17. ~~29~~. (new) The apparatus of claim ¹³~~25~~ wherein the integrated optics chip or optoelectronic device is mounted on a substrate, which is a submount chip or substrate chip.

18. ~~30~~. (new) The apparatus of claim ²⁷~~29~~ wherein the substrate cooperates with the front portion of the V-groove chip to hold the optical fiber.

19. ~~31~~. (new) The apparatus of claim ²⁷~~29~~ wherein the substrate cooperates with the front portion and middle portion of the V-groove chip to hold the optical fiber.